

8

7

6

5

4

3

2

1

F

F

E

E

D

D

C

C

B

B

A

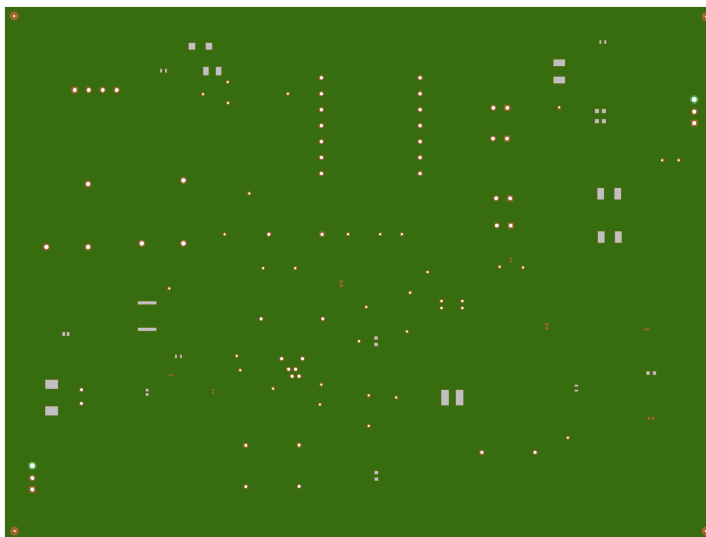
A

NOTES:













1. RIGID-FLEX TO BE FABRICATED USING IPC-6013, CLASS 2, STANDARDS.
2. RIGID-FLEX CIRCUIT CONTAINS UP TO 8 LAYERS IN RIGID SECTIONS AND 2 LAYERS IN FLEXIBLE SECTIONS.
3. MATERIALS:
 - A. RIGID MATERIAL SHALL BE EPOXY GLASS LAMINATE PER IPC- 4101 / 24 / 26 / 99 / 101 / 126.
 - B. FLEX MATERIAL SHALL BE ADHESIVELESS FLEXIBLE COPPER CLAD LAMINATE
 - C. COVERLAYER TO BE .001" POLYIMIDE WITH .001" ADHESIVE
4. COPPER STARTING WEIGHT TO BE 1/2 OZ. ON ALL LAYERS WITH AN ADDITIONAL PLATING OF .001" MIN. COPPER ON OUTER LAYERS.
5. RIGID-FLEX CIRCUIT IS A MULTIPLE BEND TYPE.
6. APPLY STRAIN RELIEF OF ECCOBOND 45/15 IN RIGID-FLEX TO FLEX TRANSITION AREA APPROXIMATELY AS SHOWN.
7. MINIMUM BEND RADII TO BE 6X THICKNESS OF FLEX CIRCUIT.
8. MINIMUM LINE WIDTH .010" AND MINIMUM LINE SPACE .010".
9. MINIMUM ANNULAR RING REQUIREMENTS IN ACCORDANCE WITH IPC-6012, CLASS 2, TANGENCY WITH NO BREAKOUT.
10. UNLESS OTHERWISE SPECIFIED HOLE TOLERANCES ARE +/- .003".
11. FINISH: AFTER COPPER PLATING PLATE ENIG, PER IPC-4552.
12. SOLDER MASK RIGID SECTION BOTH SIDES LPISM GREEN (SOLDER MASK OVER BARE COPPER).
13. RoHS MATERIALS REQUIRED.
14. OVERALL THICKNESS OF FLEX LAYERS SHALL NOT EXCEED .009".
15. SILKSCREEN COLOR WHITE ON TOP SIDE OF BOARD.
16. ALL BOARD DIMENSIONS SPECIFIED BY DWG IN ATTACHED FILE TEST.PDF. (DIMENSIONS IN GERBERS FOR REFERENCE ONLY.)
17. FOR ANY DIMENSIONS NOT IN DWG TEST.PDF USE GERBER DATA.
18. VENDOR TO PRIMARY DRILL ALL HOLES (NON-PLATED HOLES SHALL BE TENTED.)
19. MAXIMUM OF 1 X-OUTS ALLOWED IN ARRAY.

NOTES: UNLESS OTHERWISE SPECIFIED

1. MATL: Copper clad plated sheet per MIL-P-13949/4, Type GFM,
 - A. Copper Weight:
 - a) Outer Layers 1.5 OZ.
 - b) Inner Plane Layers 1 OZ.
 - c) Inner Signal Layers 1 OZ.
 - B. Laminate using Pre-Preg Material Per MIL-P-13949/12, Type PC-GF. Tg minimum 170 deg C.
2. Overall Board thickness to be .093 +/- .009.
3. Unless otherwise specified all hole dimensions apply after plating. All plated through holes to have a minimum of .001 copper.
4. All holes shall be located within .003 diameter of true position. Layer to layer registration shall be within .005. All holes surrounded by land shall have a minimum annular ring of .001. Tangency on holes with breakout is acceptable.
5. Conductor widths and spacing shall be within +/- 20% of artwork originals.
6. Apply solder mask (liquid photo imageable) over bare copper, solder mask to be per IPC-SM-84D, Type B, Class 3, Color: Transparent Green. All exposed conductive surfaces to be solder coated.
7. Ware or twist of board shall not exceed .0075 inch per inch.



3D PCB View

Drill Chart					
Qty	Size	Sym	Plated	Tolerance	
62	0.028		Yes	+0/-0.028	
4	0.030		Yes	+/-0.003	
4	0.031		Yes	+/-0.003	
16	0.039		Yes	+0/-0.039	
12	0.042		Yes	+0/-0.042	
8	0.043		Yes	+0/-0.043	
28	0.047		Yes	+0/-0.047	
16	0.053		Yes	+0/-0.053	
8	0.057		Yes	+0/-0.057	
8	0.058		Yes	+0/-0.058	
12	0.063		Yes	+0/-0.063	
4	0.125		No	+/-0.002	

NEXT ASSY	USED ON
APPLICATION	

РАЗМЕРЫ И ДРУГИЕ ХАРАКТЕРИСТИКИ ПЕЧАТНОЙ ПЛАТЫ ВВОДЯТСЯ ВРУЧНУЮ			
TOLERANCE ON:			
1%	1%	1%	
MATL	N/A		
HARD	CLASS 1	CASE DEPTH	1.65mm
SURF TREAT	FR-4		

REVISIONS			
REV	DESCRIPTION	DATE	APPROVED

	27.06.2024	BP			
ENGINEER CHEREPANOV I.R.	DATE				
CHECKED MOLGANOV A.A.	DATE				
APPROVED N/A	DATE				
ISSUED CHEREPANOV I.R.	DATE	SIZE C	CAGE CODE 0.1.0	DWG YES	REV A
		SCALE 1 : 1		SHEET 1 OF 1	

